



Material Content Data Sheet



Sales Product Name		BTS7004-1EPP		Issued		12. February 2019		
MA#		MA004987070						
Package		PG-TSDSO-14-22		Weight*		65.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.355	2.08	2.08	20755	20755
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.038	0.06		578	
	non noble metal	iron	7439-89-6	0.754	1.16		11551	
wire	non noble metal	copper	7440-50-8	30.617	46.91	48.14	469006	481279
	non noble metal	copper	7440-50-8	0.792	1.21	1.21	12137	12137
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1324
plastics	plastics	epoxy resin	-	3.371	5.16		51638	
	inorganic material	silicondioxide	60676-86-0	25.354	38.84	44.13	388387	441349
leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25147	25147
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12501	12501
glue	plastics	epoxy resin	-	0.078	0.12		1196	
	noble metal	silver	7440-22-4	0.368	0.56	0.68	5636	6832
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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